

N-Ch 30V Fast Switching MOSFETs

RC80N03

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary

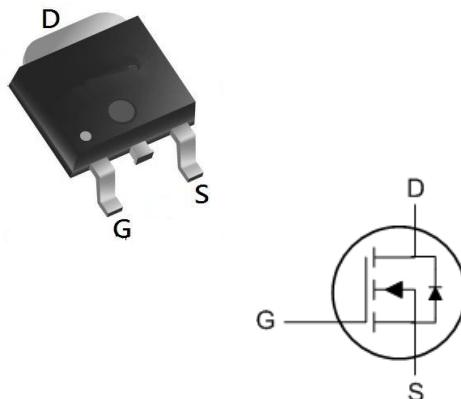
BVDSS	RDS(ON)	ID
30V	4.8mΩ	80 A

Description

The RC80N03 is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The RC80N03 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

TO252 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		10s	Steady State	
V _{DS}	Drain-Source Voltage	30		V
V _{GS}	Gate-Source Voltage	±20		V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	80		A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	50		A
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	30	19	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	25	16	A
I _{DM}	Pulsed Drain Current ²	192		A
EAS	Single Pulse Avalanche Energy ³	144.7		mJ
I _{AS}	Avalanche Current	53.8		A
P _D @T _C =25°C	Total Power Dissipation ⁴	62.5		W
P _D @T _A =25°C	Total Power Dissipation ⁴	6	2.42	W
T _{STG}	Storage Temperature Range	-55 to 175		°C
T _J	Operating Junction Temperature Range	-55 to 175		°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	62	°C/W
R _{θJA}	Thermal Resistance Junction-Ambient ¹ (t ≤ 10s)	---	25	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	2.4	°C/W

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Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	30	---	----	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.0213	-6	V°C
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{GS}=10\text{V}$, $I_D=30\text{A}$	---	4.8	9	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=15\text{A}$	---	7.8		
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-5.73	---	mV°C
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=24\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	uA
		$V_{DS}=24\text{V}$, $V_{GS}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=5\text{V}$, $I_D=30\text{A}$	---	26.5	---	S
R_g	Gate Resistance	$V_{DS}=0\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	---	1.4	2.8	Ω
Q_g	Total Gate Charge (4.5V)	$V_{DS}=15\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=15\text{A}$	---	31.6	----	nC
Q_{gs}	Gate-Source Charge		---	8.6	----	
Q_{gd}	Gate-Drain Charge		---	11.7	----	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=15\text{V}$, $V_{GS}=10\text{V}$, $R_G=3.3\Omega$	---	9	----	ns
T_r	Rise Time		---	19	--	
$T_{d(off)}$	Turn-Off Delay Time		---	58		
T_f	Fall Time		---	15.2	---	
C_{iss}	Input Capacitance	$V_{DS}=15\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	---	3075	4000	pF
C_{oss}	Output Capacitance		---	400	530	
C_{rss}	Reverse Transfer Capacitance		---	315	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	80	A
I_{SM}			---	---	132	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0\text{V}$, $I_S=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V
t_{rr}	Reverse Recovery Time	$ I_F =30\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$, T_J	---	18	---	nS
Q_{rr}	Reverse Recovery Charge	$=25^\circ\text{C}$	---	8	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=25\text{V}$, $V_{GS}=10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=53.8\text{A}$
- 4.The power dissipation is limited by 175°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

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Typical Characteristics

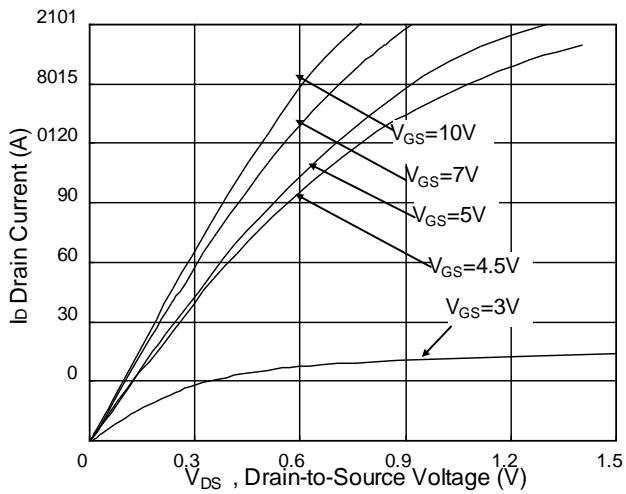


Fig.1 Typical Output Characteristics

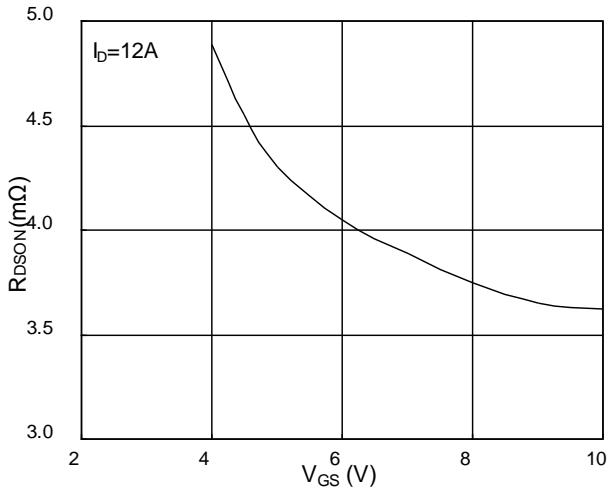


Fig.2 On-Resistance vs. G-S Voltage

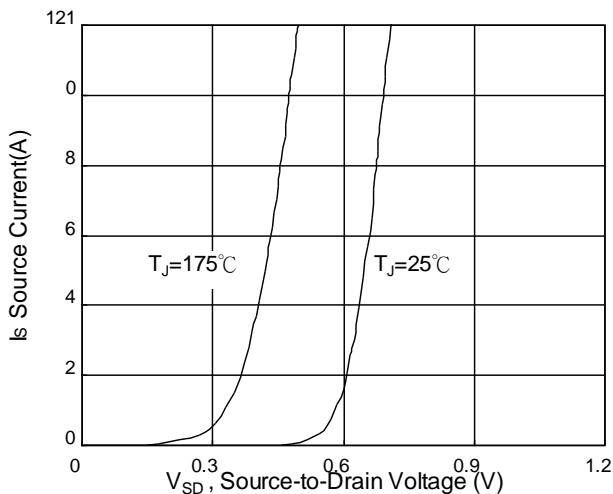


Fig.3 Forward Characteristics of Reverse

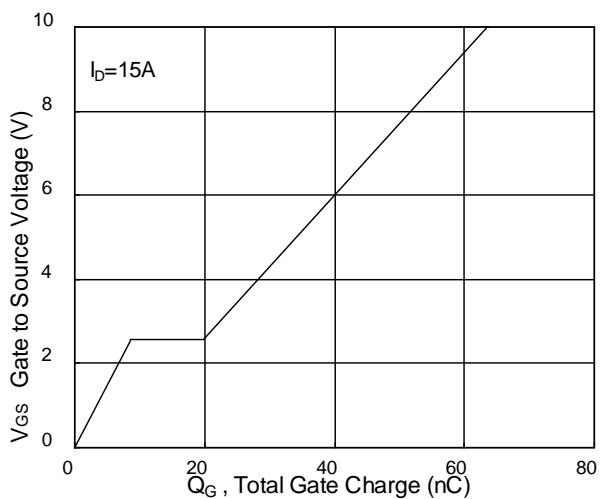


Fig.4 Gate-Charge Characteristics

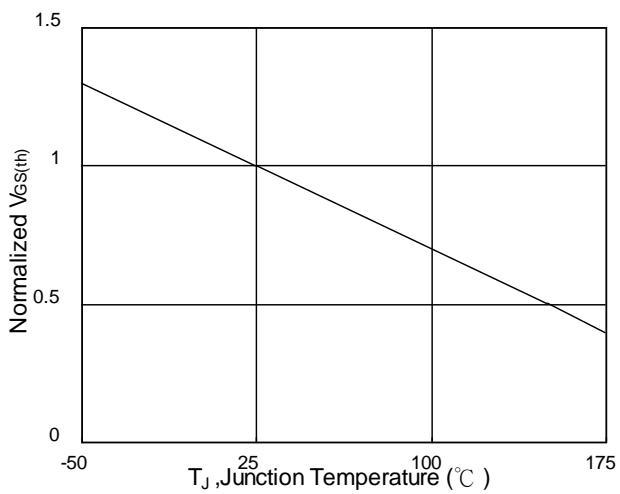


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

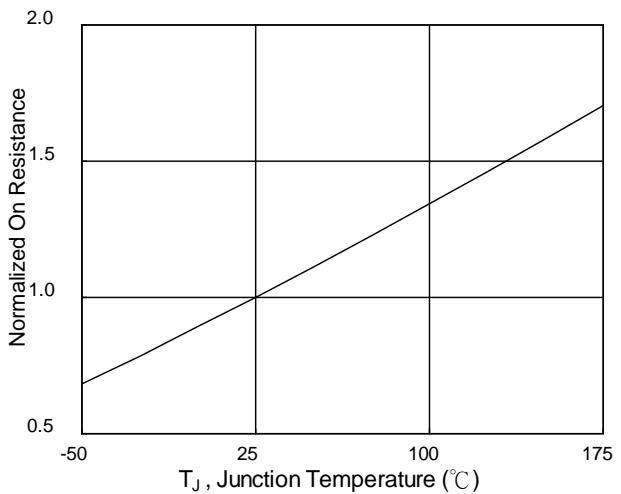


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

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